

1/17

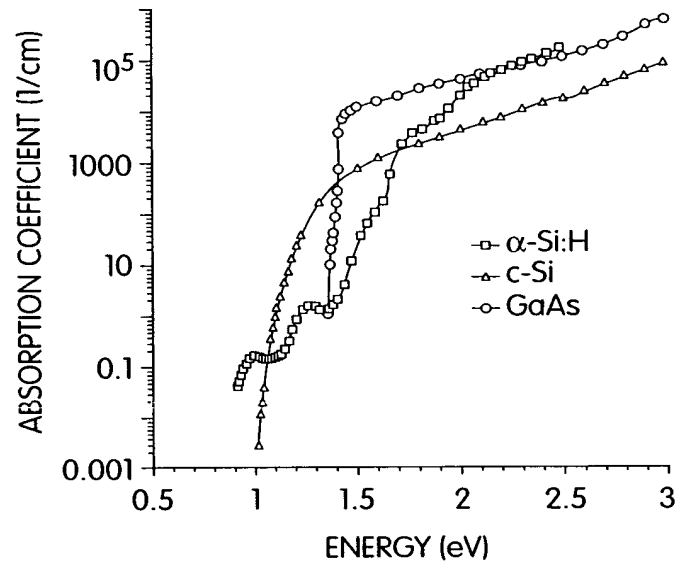


Fig. 1

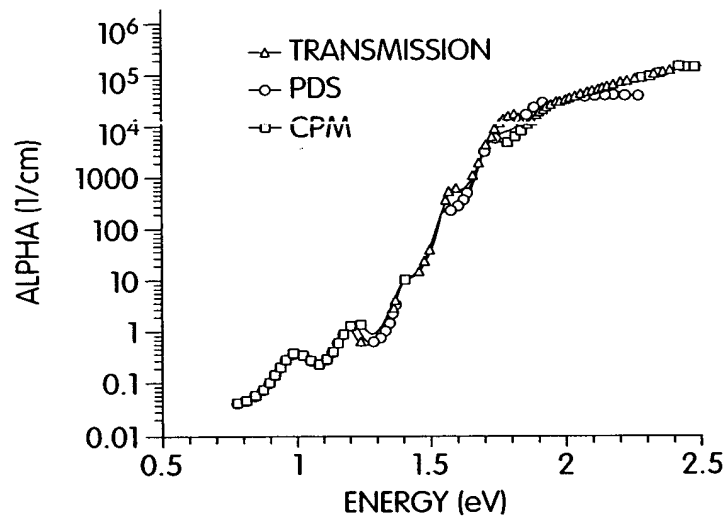


Fig. 2

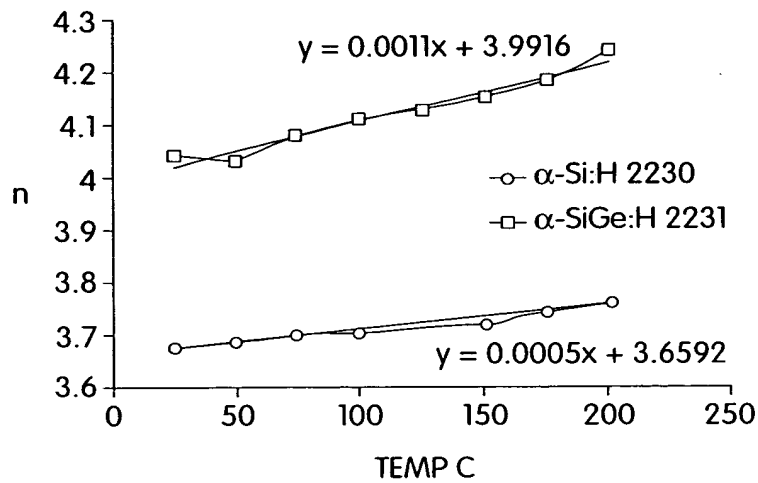


Fig. 3

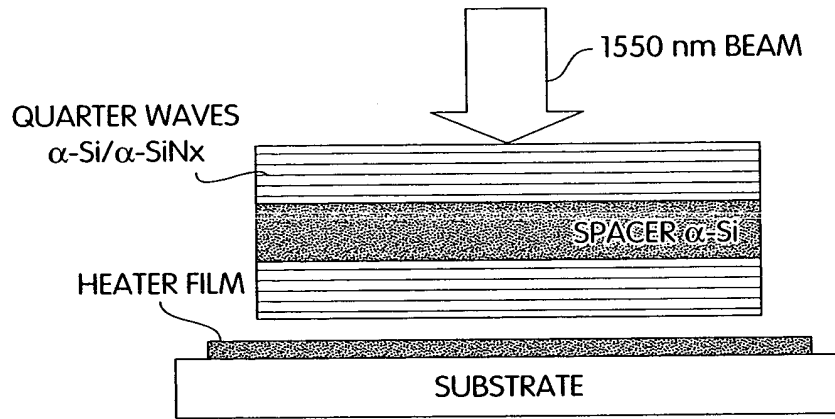


Fig. 4

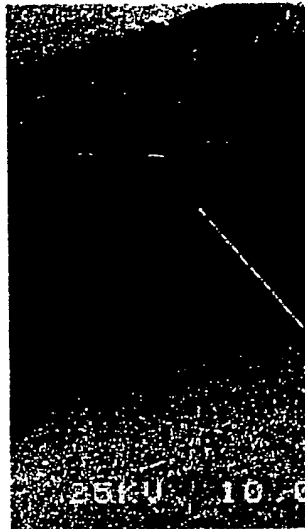


Fig. 5

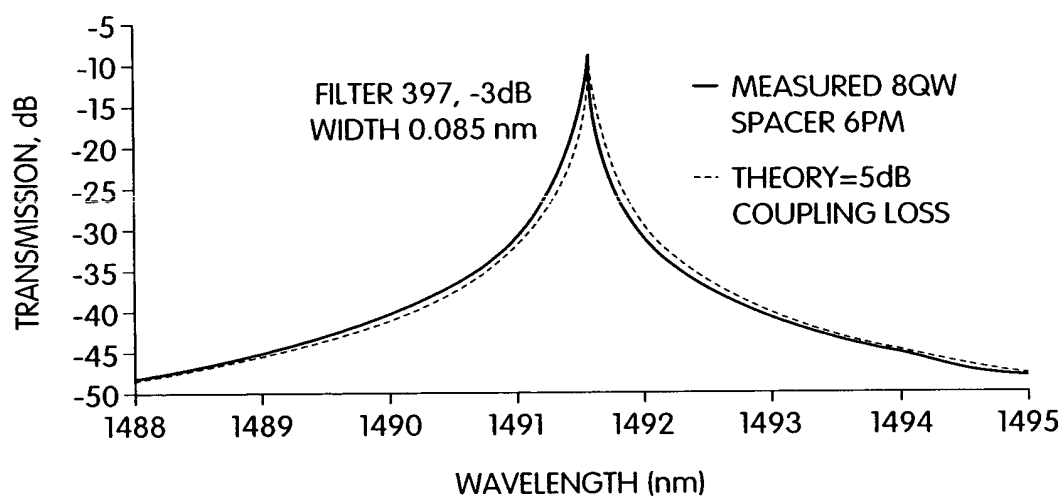


Fig. 6

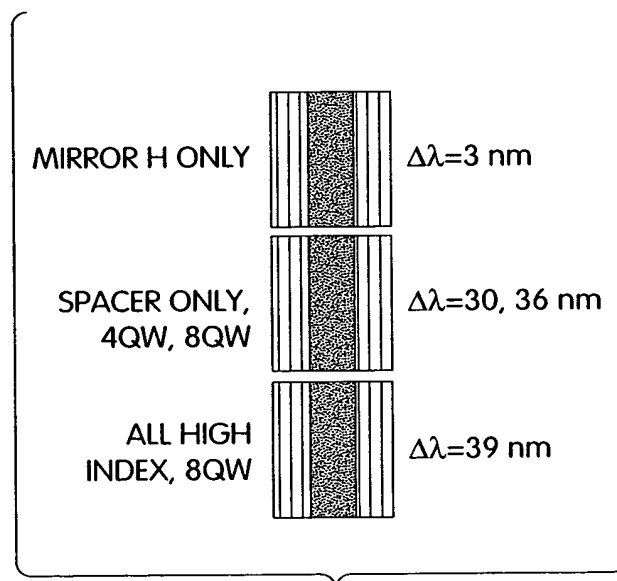


Fig. 7

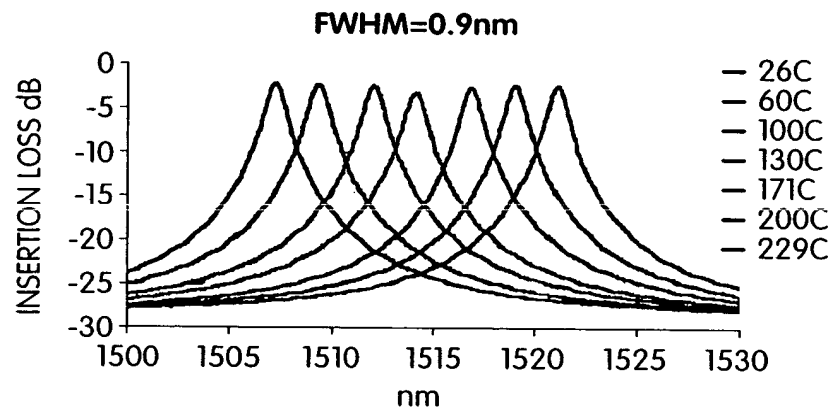


Fig. 8

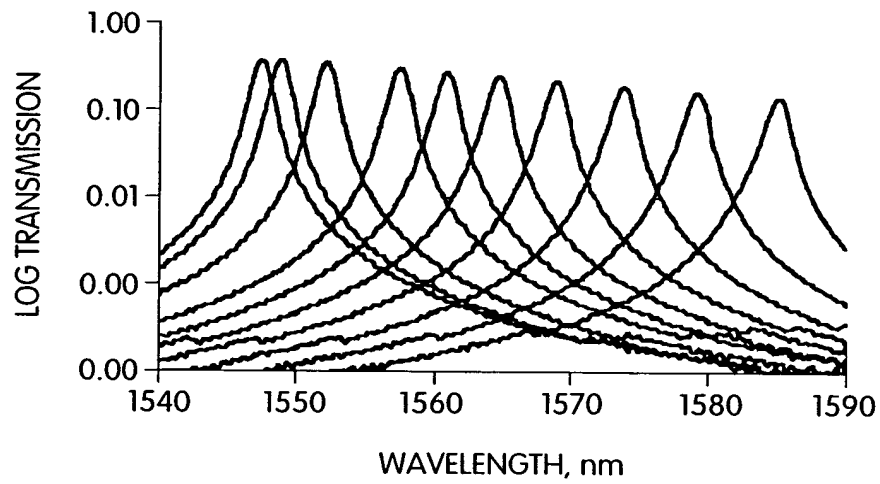


Fig. 9

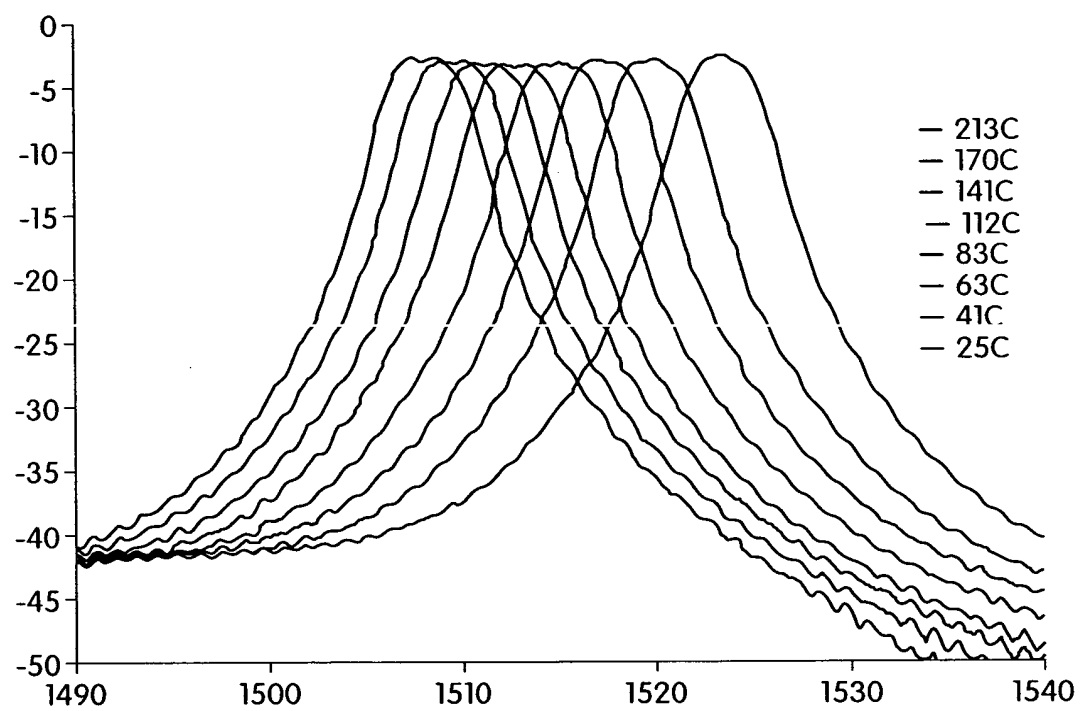


Fig. 10

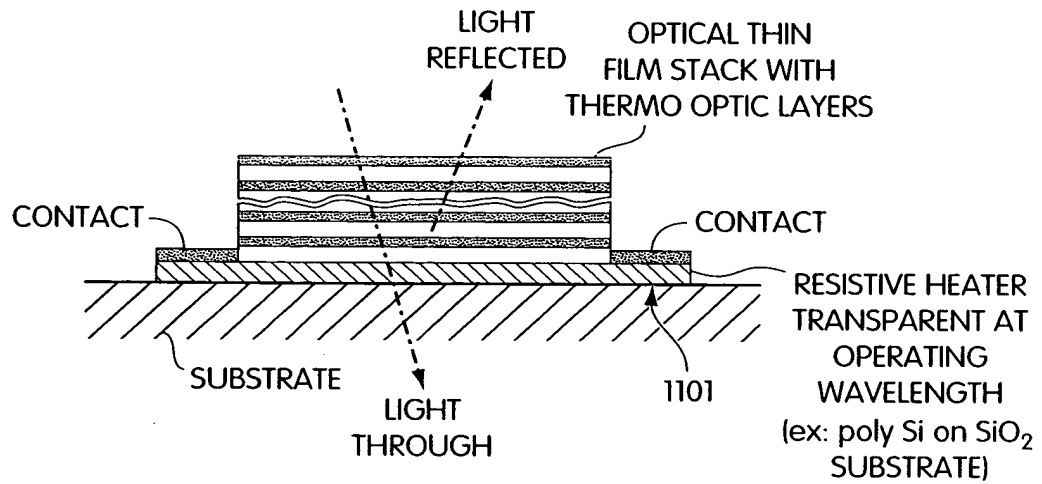


Fig. 11

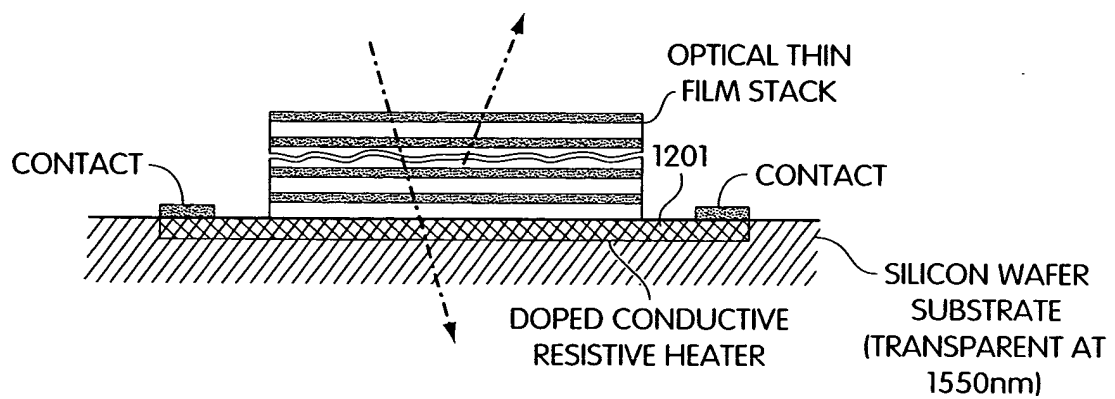


Fig. 12

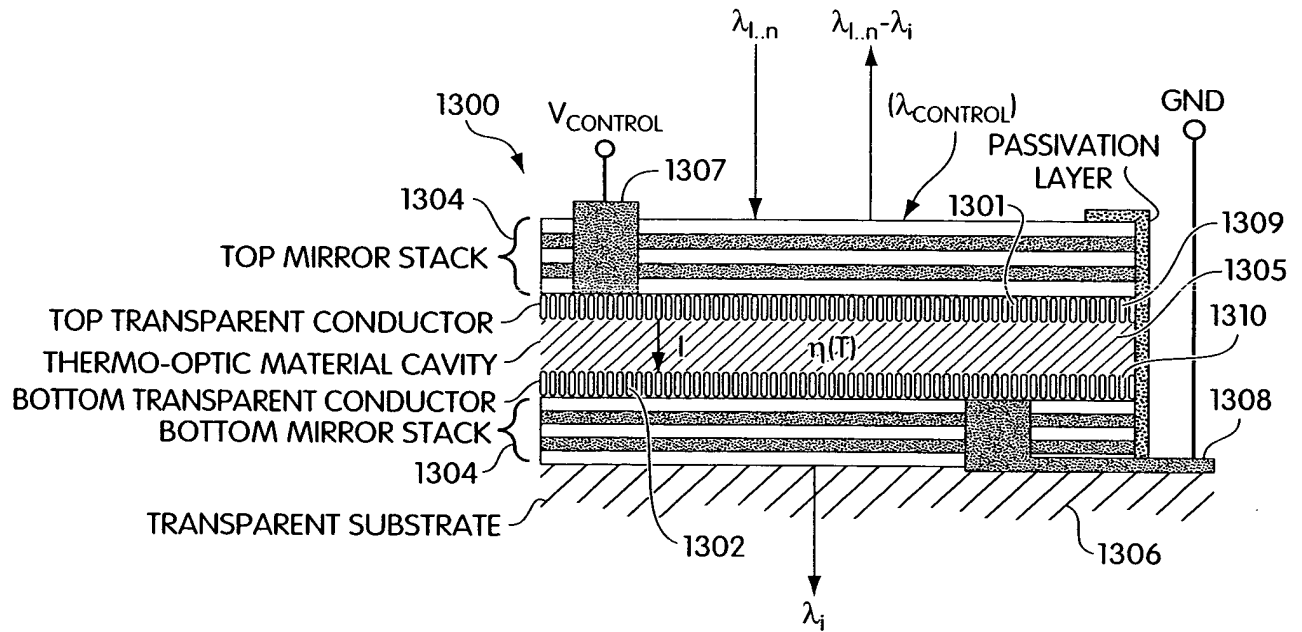


Fig. 13

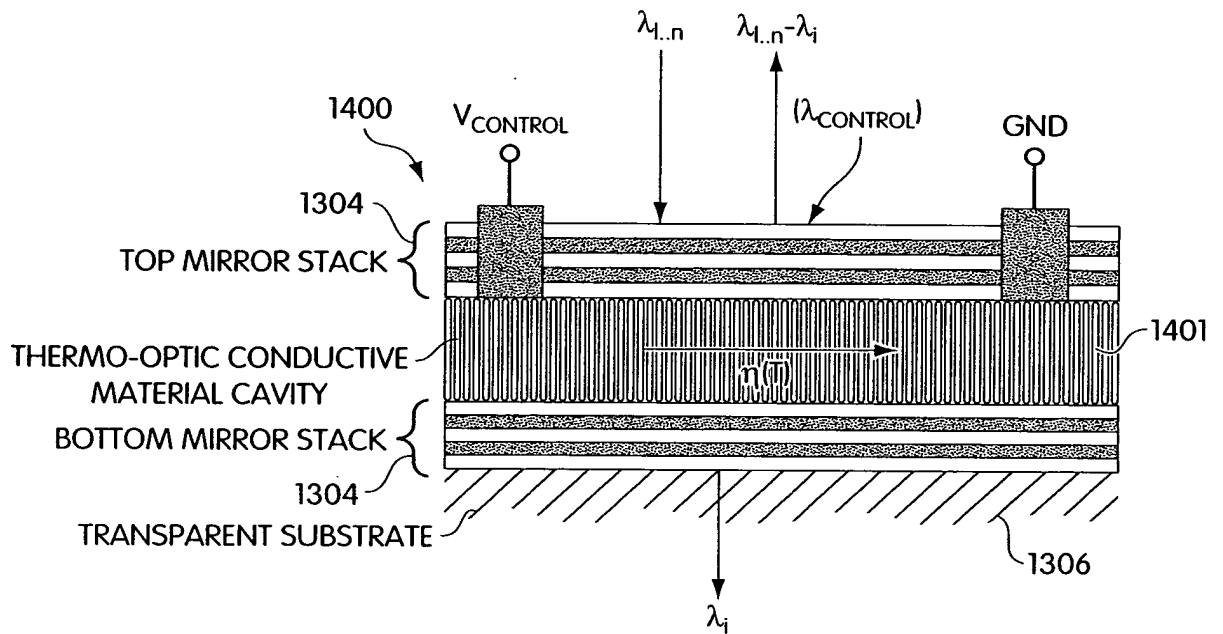


Fig. 14

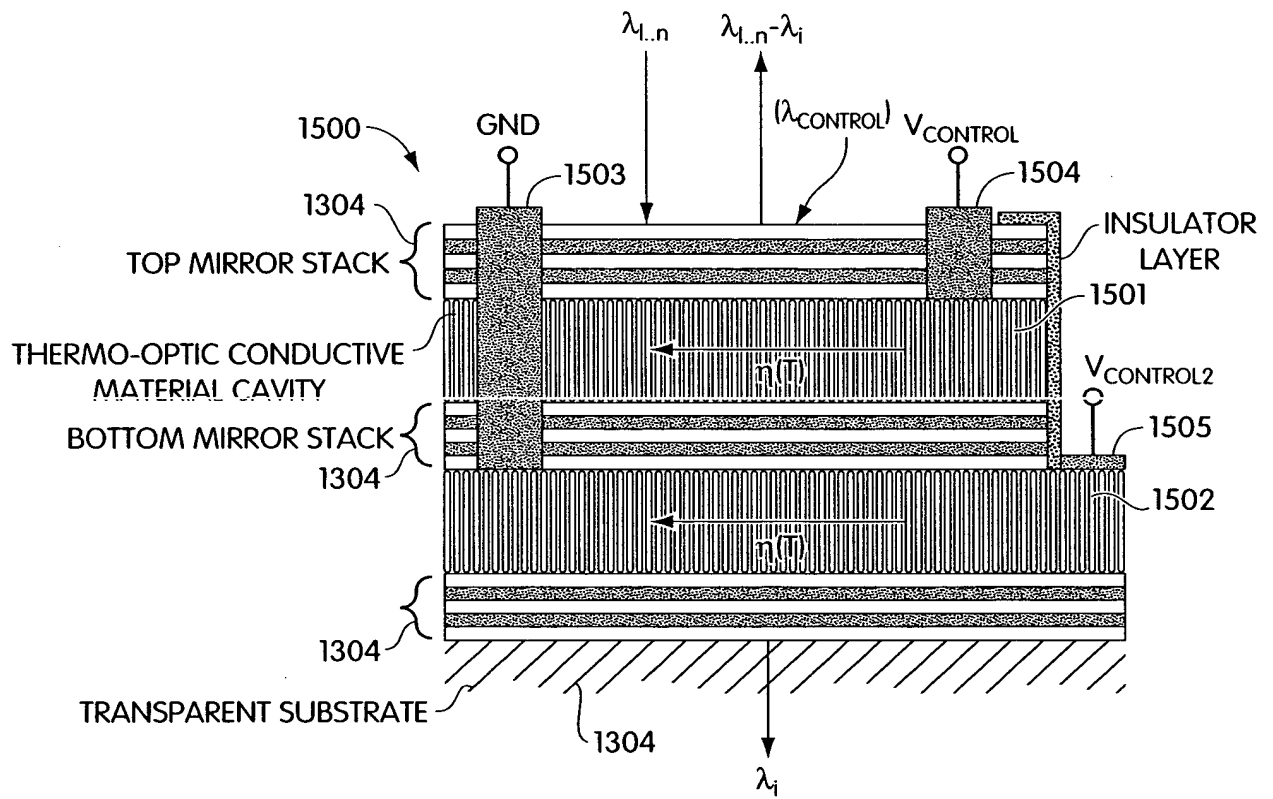


Fig. 15

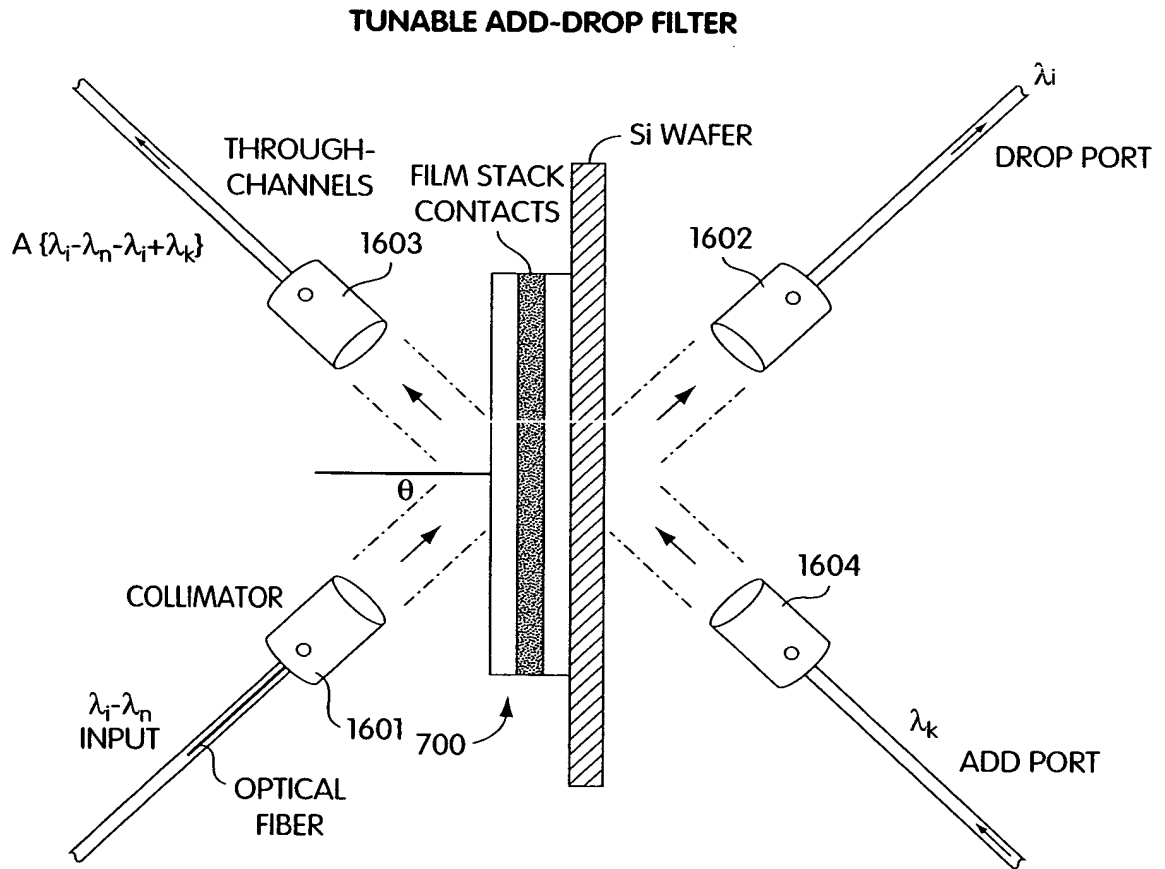


Fig. 16

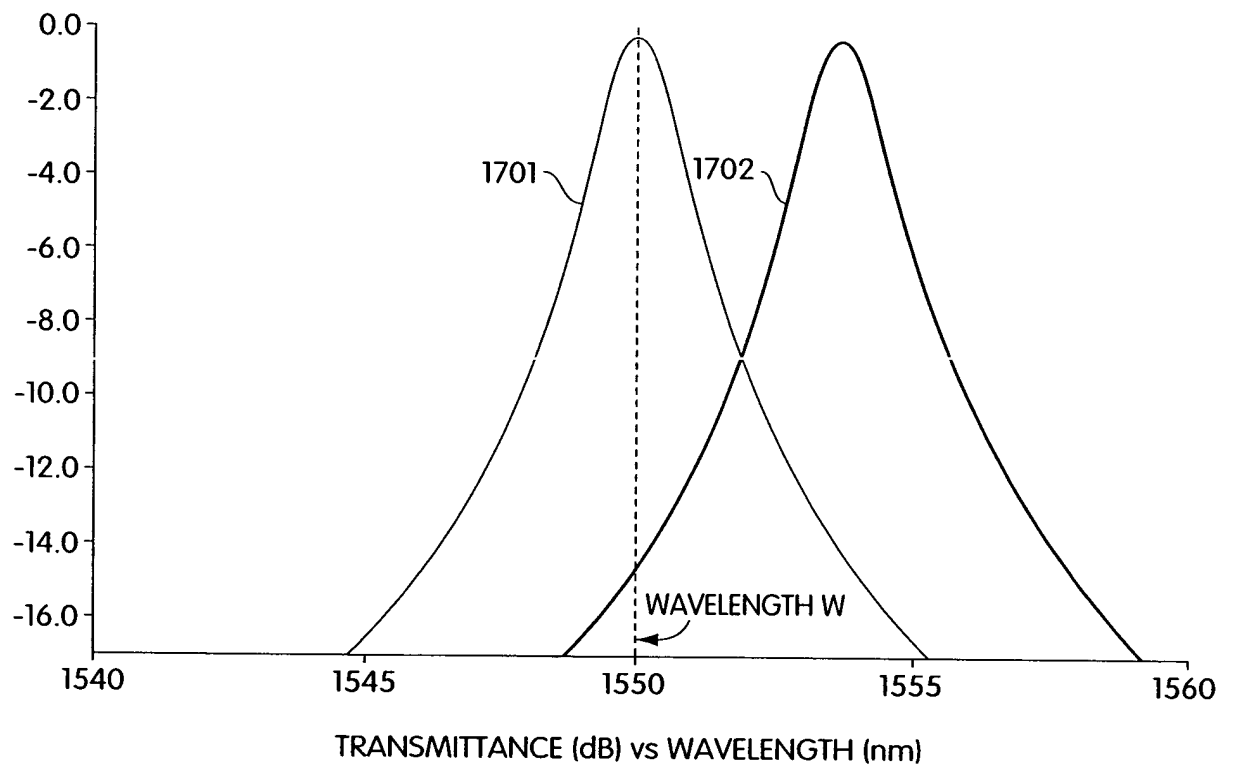
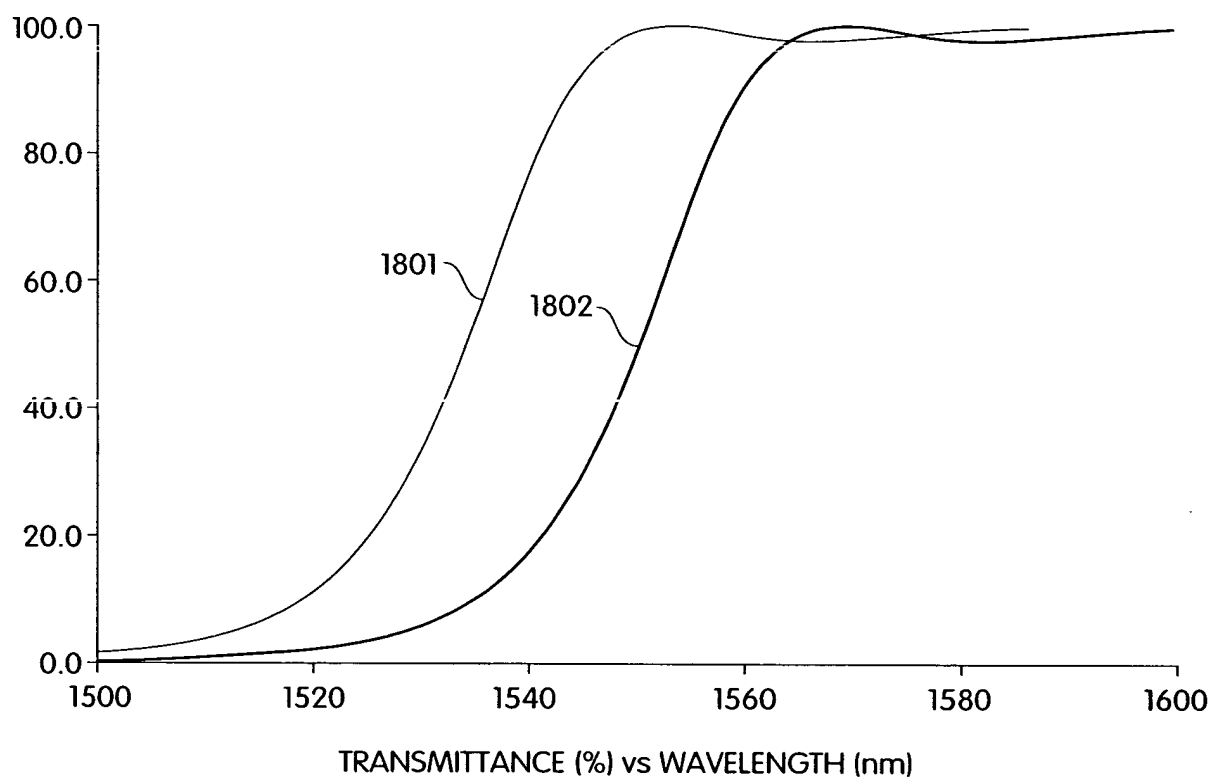


Fig. 17

**Fig. 18**

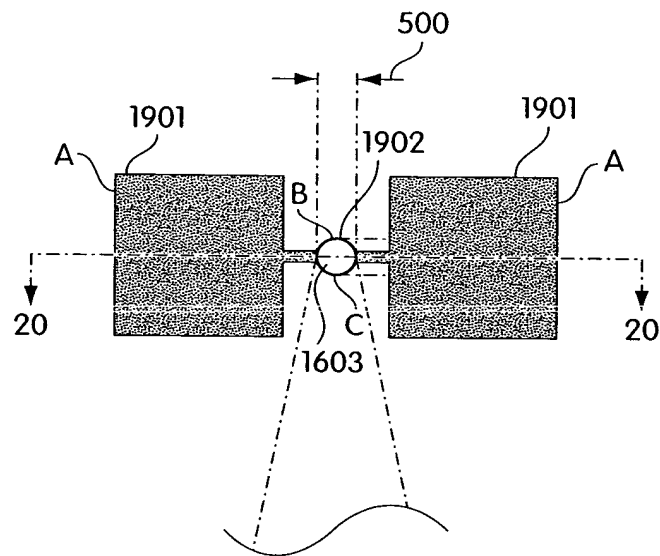


Fig. 19

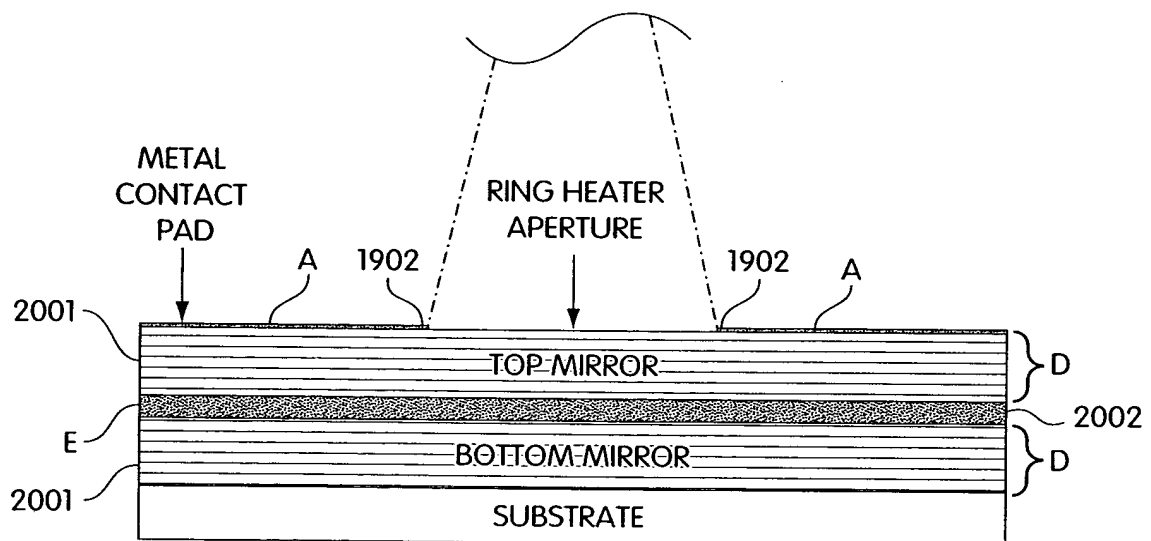


Fig. 20

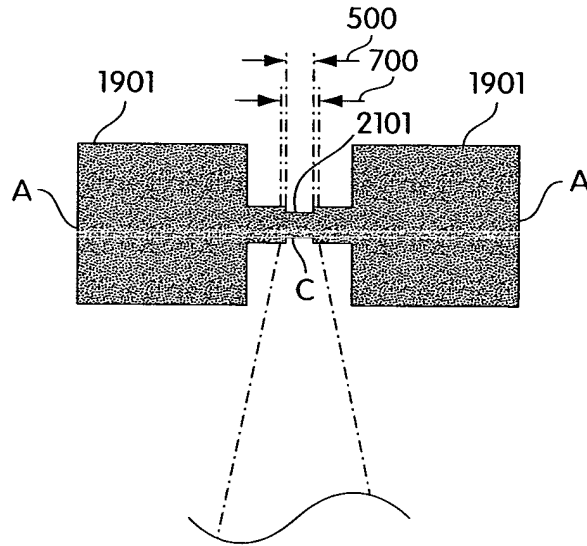


Fig. 21

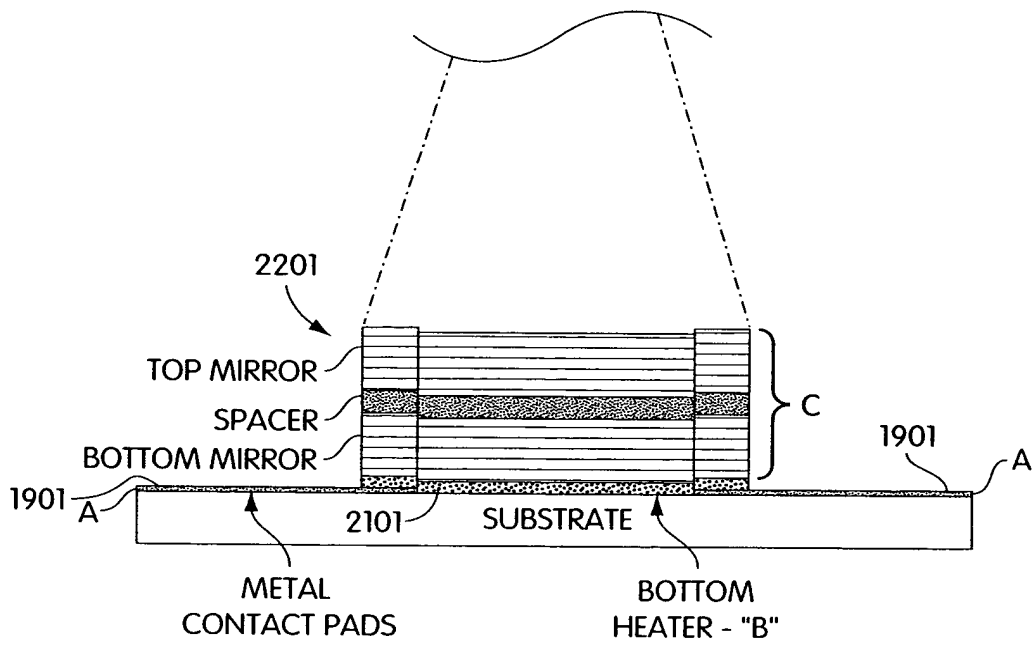


Fig. 22

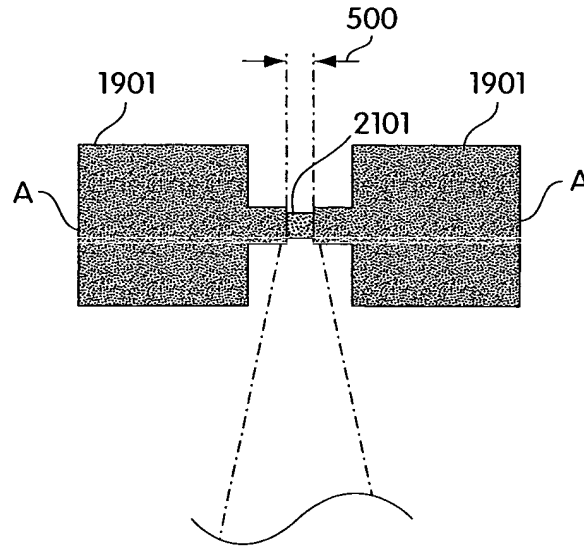


Fig. 23

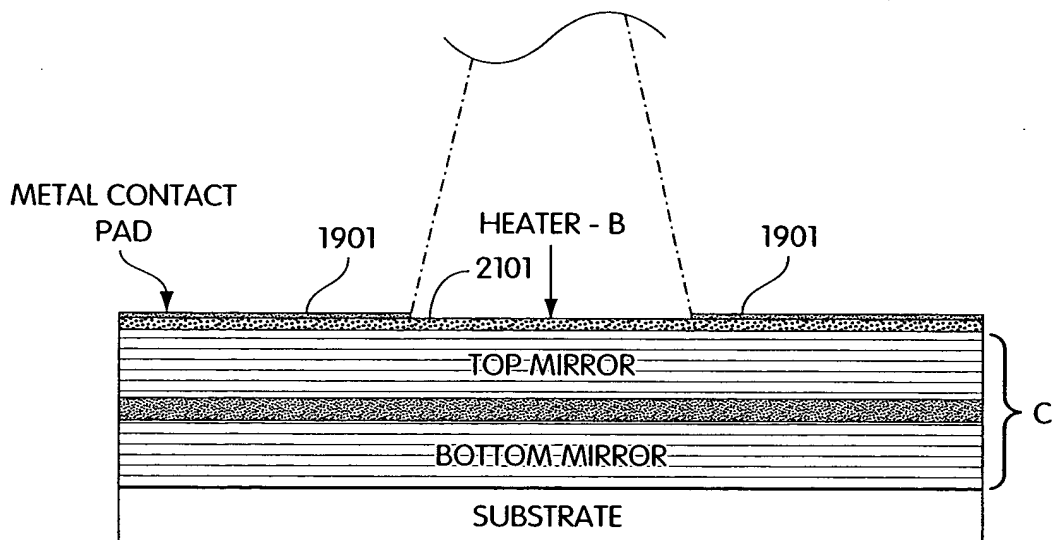


Fig. 24

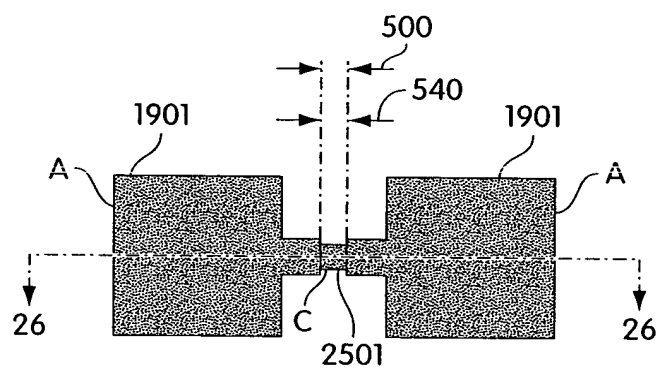


Fig. 25

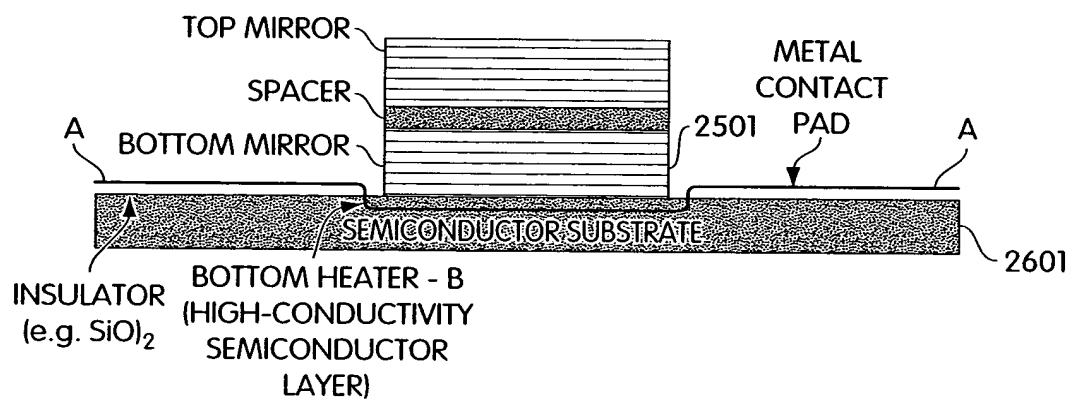


Fig. 26

A cross-sectional view of a device 2101 mounted on a substrate. The device 2101 consists of a central stack of layers: a TOP MIRROR, a SPACER, and a BOTTOM MIRROR, which are collectively labeled with a bracket 'C'. This stack is flanked by TOP HEATER - B and BOTTOM HEATER - "B". The entire assembly is supported by a SUBSTRATE. A layer labeled 'A' is shown at the base of the device and on the sides of the central stack. METAL CONTACT PADS are indicated at the bottom of the device. Dashed lines from the top of the device point to a curved line above it.

Fig. 28

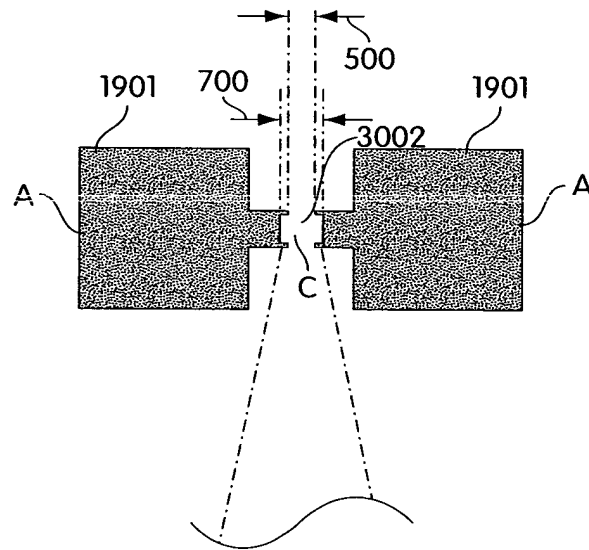


Fig. 29

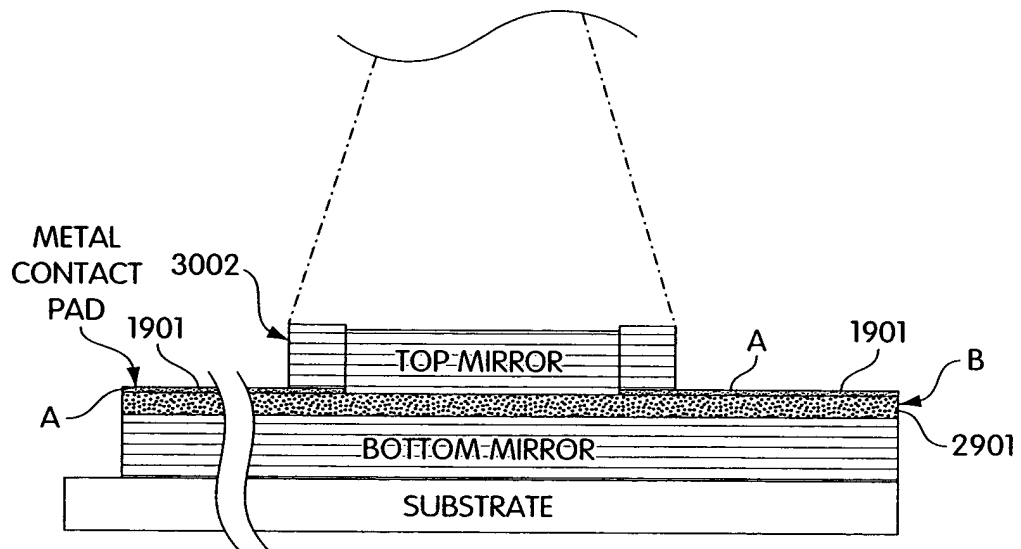


Fig. 30